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# HAT2068R

Silicon N Channel Power MOS FET Power Switching

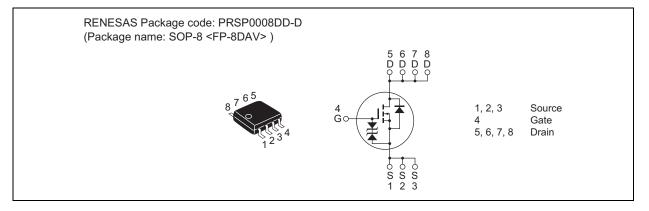
REJ03G1176-0500 (Previous: ADE-208-1225C) Rev.5.00 Sep 07, 2005

# Features

- Capable of 4.5 V gate drive
- Low drive current
- High density mounting
- Low on-resistance

 $R_{DS (on)} = 7 \text{ m}\Omega \text{ typ.} (at V_{GS} = 10 \text{ V})$ 

## Outline





# **Absolute Maximum Ratings**

			$(Ta = 25^{\circ}C)$
ltem	Symbol	Value	Unit
Drain to source voltage	V <sub>DSS</sub>	30	V
Gate to source voltage	V <sub>GSS</sub>	±20	V
Drain current	ID	14	А
Drain peak current	I <sub>D (pulse)</sub> Note 1	112	A
Body-drain diode reverse drain current	I <sub>DR</sub>	14	А
Channel dissipation	Pch Note 2	2.5	W
Channel to ambient thermal impedance	θ ch-a <sup>Note 2</sup>	50	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu s,$  duty cycle  $\leq$  1%

2. When using the glass epoxy board (FR4 40  $\times$  40  $\times$  1.6 mm), PW  $\leq$  10 s

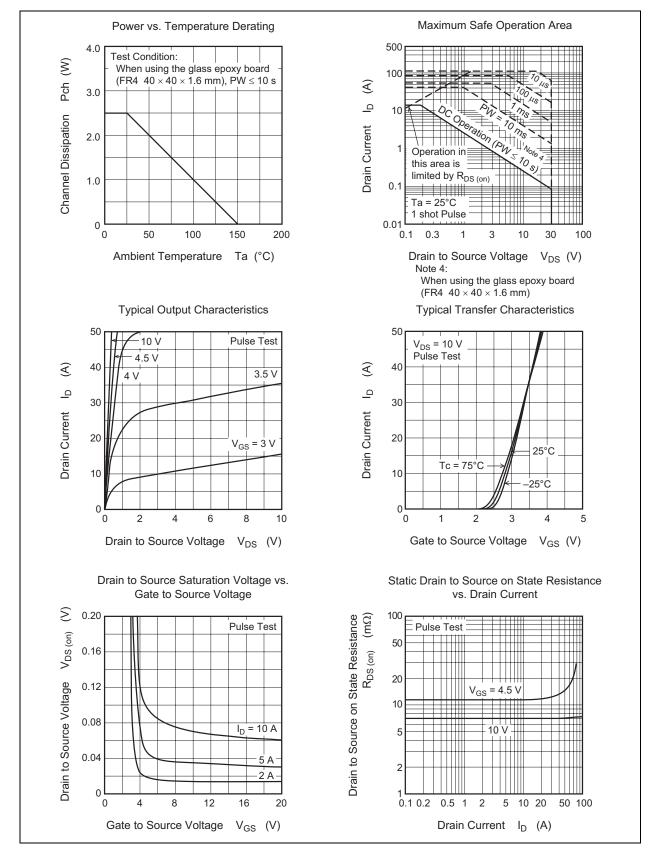
## **Electrical Characteristics**

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V (BR) DSS	30	—	—	V	$I_{D} = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V (BR) GSS	±20	—	—	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I <sub>GSS</sub>	—	—	±10	μA	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	—	_	1	μA	$V_{DS} = 30 V, V_{GS} = 0$
Gate to source cutoff voltage	V <sub>GS (off)</sub>	1.0	—	2.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Static drain to source on state resistance	R <sub>DS (on)</sub>	—	7	9	mΩ	$I_D = 7 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note 3}}$
	R <sub>DS (on)</sub>	—	11	16	mΩ	$I_D = 7 \text{ A}, V_{GS} = 4.5 \text{ V}^{Note 3}$
Forward transfer admittance	y <sub>fs</sub>	16	28	—	S	$I_D = 7 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss	—	1650	—	pF	V <sub>DS</sub> = 10 V
Output capacitance	Coss	—	400	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	—	220	—	pF	f = 1 MHz
Total gate charge	Qg	—	26	—	nC	V <sub>DD</sub> = 10 V
Gate to source charge	Qgs	—	5	—	nC	V <sub>GS</sub> = 10 V
Gate to drain charge	Qgd	—	5	—	nC	I <sub>D</sub> = 14 A
Turn-on delay time	t <sub>d (on)</sub>	—	15	_	ns	$V_{GS} = 10 \text{ V}, I_D = 7 \text{ A}$
Rise time	tr	—	30	—	ns	$V_{DD} \approx 10 \ V$
Turn-off delay time	t <sub>d (off)</sub>	—	50	—	ns	$R_L = 1.43 \Omega$
Fall time	t <sub>f</sub>	—	10		ns	Rg = 4.7 Ω
Body-drain diode forward voltage	V <sub>DF</sub>	—	0.80	1.10	V	$I_F = 14 \text{ A}, V_{GS} = 0^{Note 3}$
Body-drain diode reverse recovery time	t <sub>rr</sub>	—	50		ns	$I_F = 14 \text{ A}, V_{GS} = 0$
						di <sub>F</sub> /dt = 50 A/µs

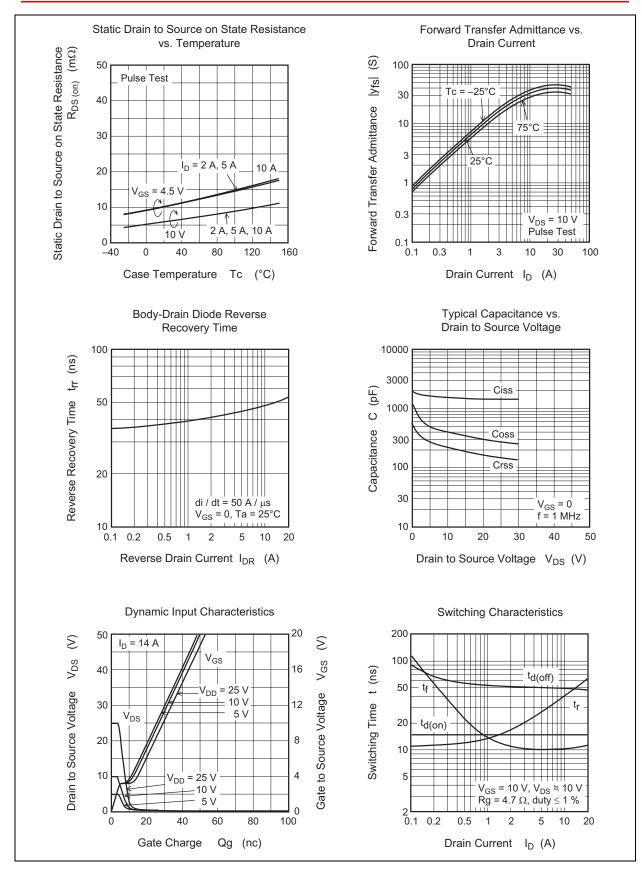
Note: 3. Pulse test



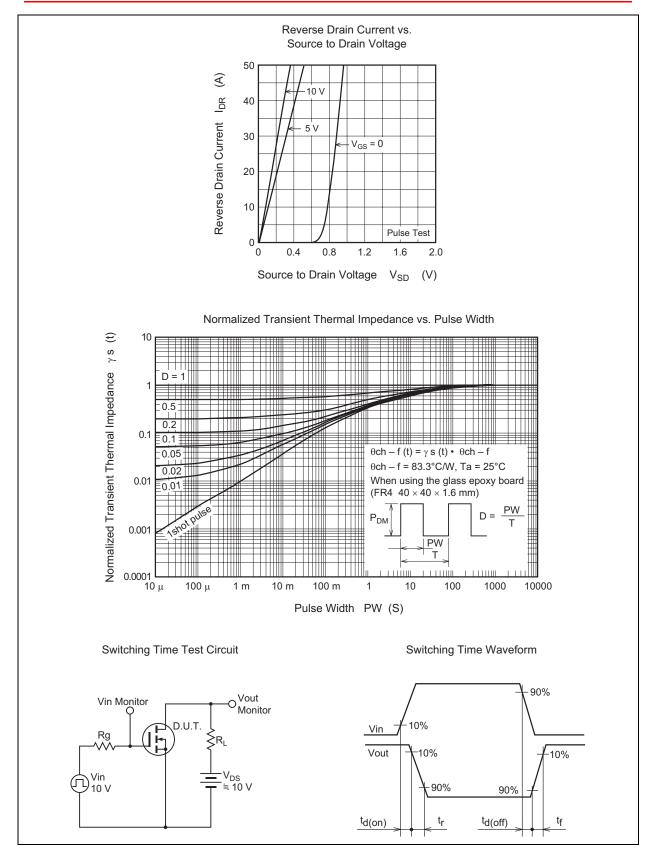
### **Main Characteristics**





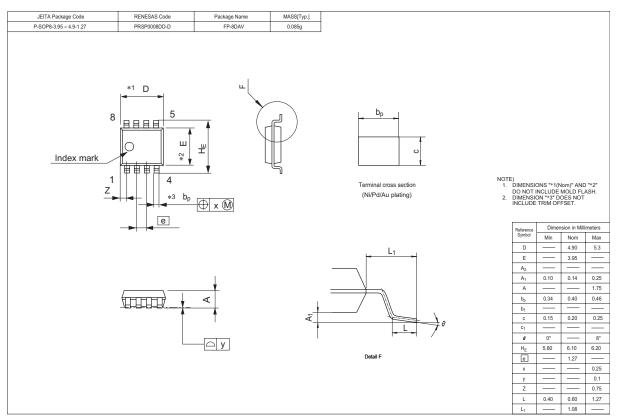






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# **Package Dimensions**



# **Ordering Information**

Part Name	Quantity	Shipping Container
HAT2068R-EL-E	2500 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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